

Title (en)

RESIN COMPOSITION, MOLDED ARTICLE, AND METHOD FOR PRODUCING MOLDED ARTICLE

Title (de)

HARZZUSAMMENSETZUNG, FORMKÖRPER UND VERFAHREN ZUR HERSTELLUNG EINES FORMKÖRPERS

Title (fr)

COMPOSITION DE RÉSINE, ARTICLE MOULÉ, ET PROCÉDÉ DE FABRICATION DE CELUI-CI

Publication

EP 4108723 A4 20240320 (EN)

Application

EP 21767966 A 20210305

Priority

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- JP 2021008754 W 20210305

Abstract (en)

[origin: EP4108723A1] The disclosure provides a resin composition having high heat dissipation and low relative permittivity while also having excellent moldability. The disclosure relates to a resin composition containing: a melt-fabricable fluororesin containing at least one functional group selected from the group consisting of a carbonyl group-containing group and a hydroxy group; at least one fluorine-free resin selected from the group consisting of a liquid crystal polymer, a polyarylene sulfide, and an aromatic polyether ketone; and particulate boron nitride.

IPC 8 full level

C08L 27/18 (2006.01); **C08K 3/38** (2006.01); **C08L 27/12** (2006.01); **C08L 71/08** (2006.01)

CPC (source: EP KR US)

C08K 3/38 (2013.01 - KR); **C08L 27/18** (2013.01 - EP KR US); **C08L 67/00** (2013.01 - US); **C08L 71/10** (2013.01 - KR); **C08L 81/02** (2013.01 - EP KR); **C08F 214/262** (2013.01 - EP); **C08G 2650/40** (2013.01 - EP); **C08K 2003/385** (2013.01 - EP KR)

C-Set (source: EP)

1. **C08L 27/18** + **C08K 3/38** + **C08L 67/04**
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3. **C08L 27/18** + **C08K 3/38** + **C08L 81/04**
4. **C08L 27/18** + **C08K 3/38** + **C08L 71/08**
5. **C08L 27/18** + **C08K 3/38** + **C08L 61/16**

Citation (search report)

- [Y] CN 110511533 A 20191129 - UNIV JILIN
- [Y] WO 2020045260 A1 20200305 - DAIKIN IND LTD [JP]
- [Y] US 2018051158 A1 20180222 - NAM PHAM HOAI [JP], et al
- [A] WO 2019225694 A1 20191128 - DAIKIN IND LTD [JP]
- [A] US 2013085220 A1 20130404 - SUPRIYA LAKSHMI [US], et al
- See also references of WO 2021182336A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

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